

BR2N7002K2Q



DATA SHEET

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/ Descriptions

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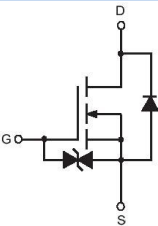
/ Features

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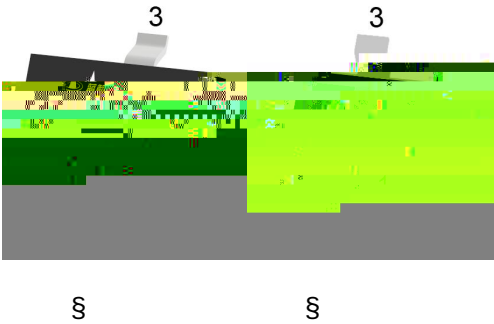
/ Applications

L Ä Å Æ % Ç È ° É S μ - C w x g h f L % y A u v ¨

/ Equivalent Circuit



/ Pinning



/ Marking

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	(℃)		
	(℃)		
			℃
		~	℃
	θ		℃
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-

/ Electrical Characteristics(Ta=25)

—		Ω				
—						

/ Electrical Characteristic Curve

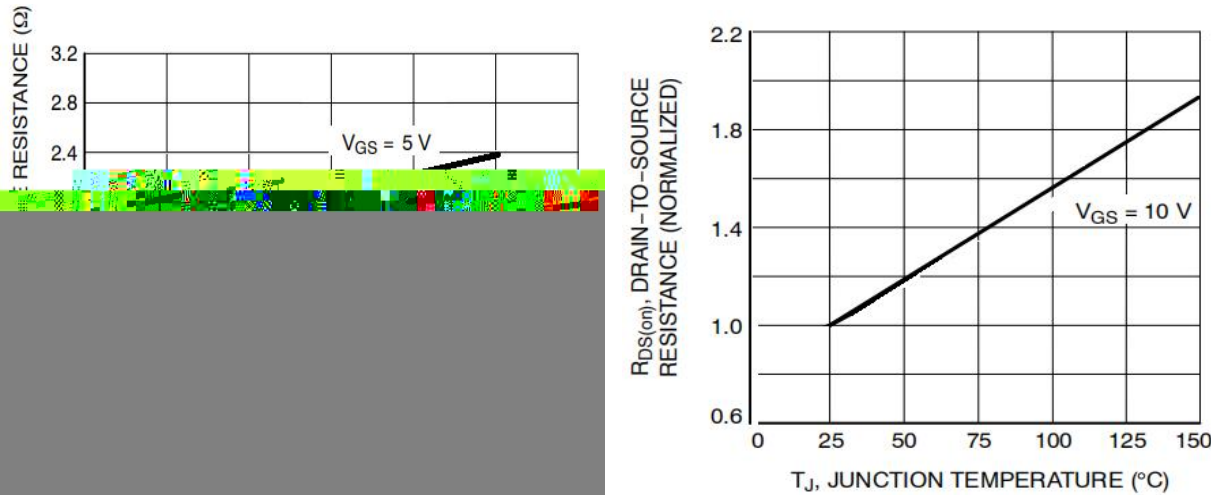
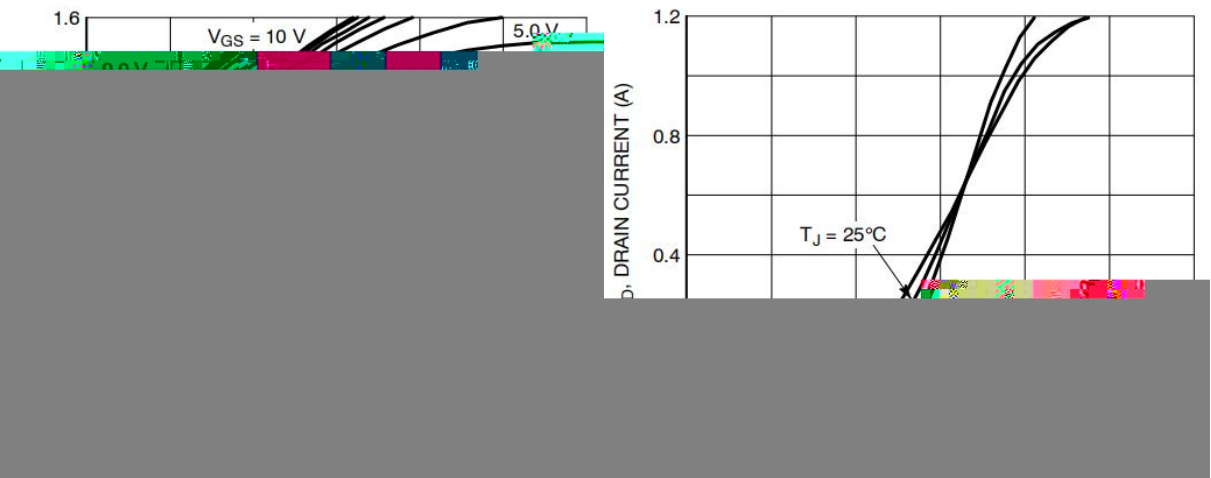
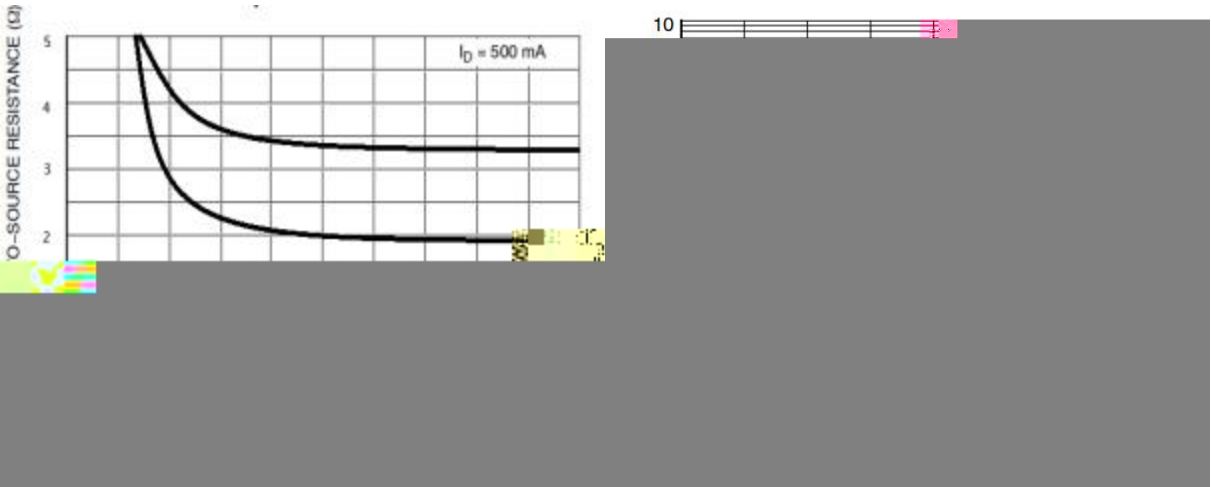


Figure 4 On-Resistance Variation with Temperature





/ Electrical Characteristic Curve

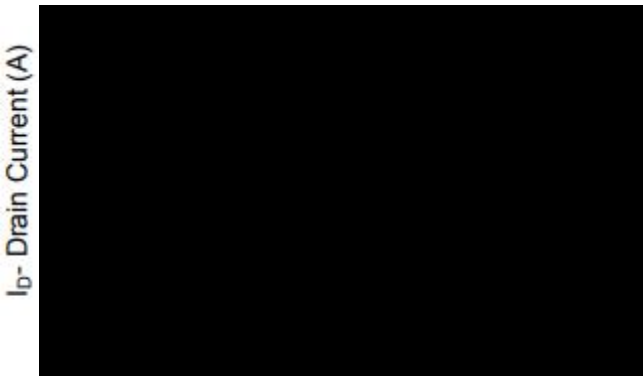
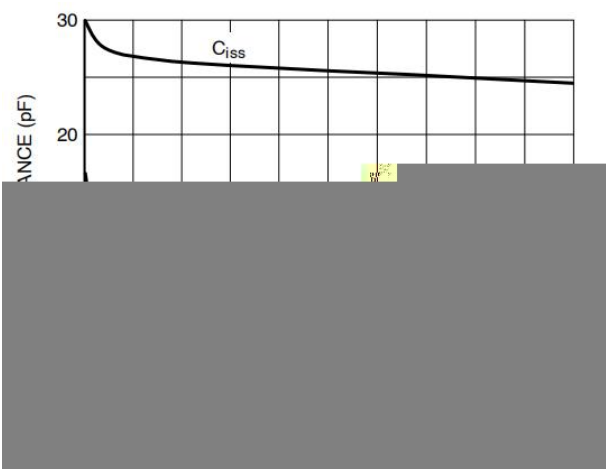
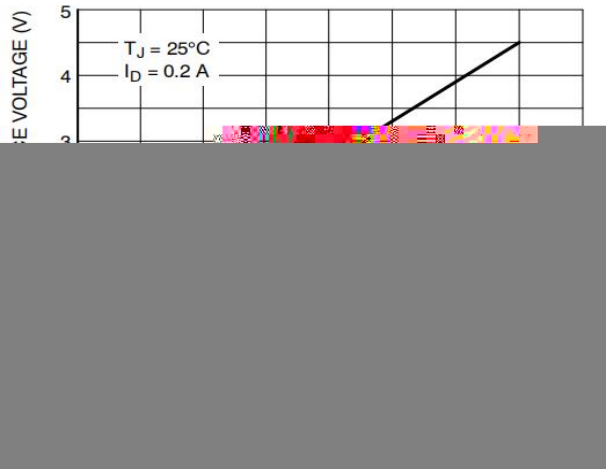
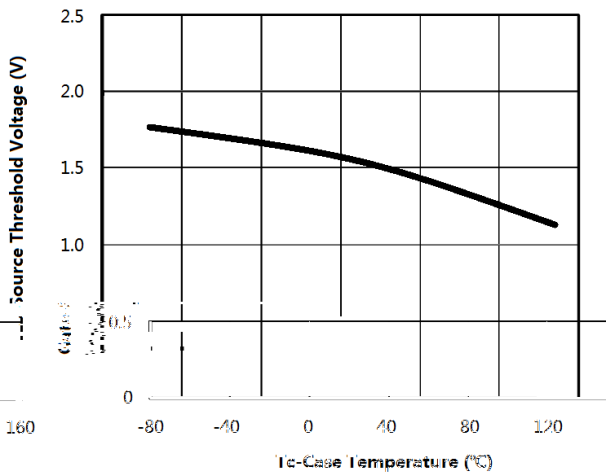
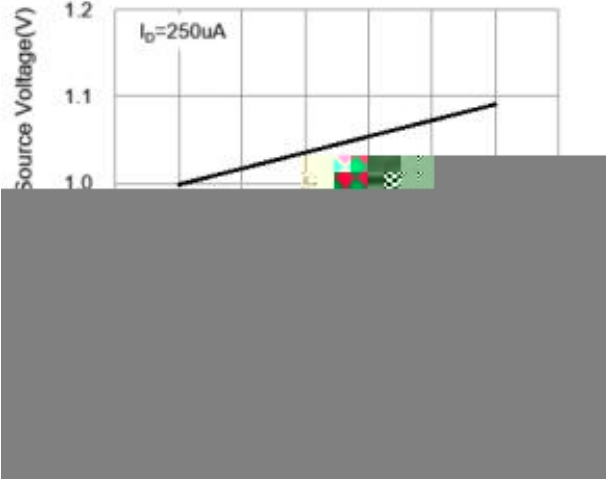
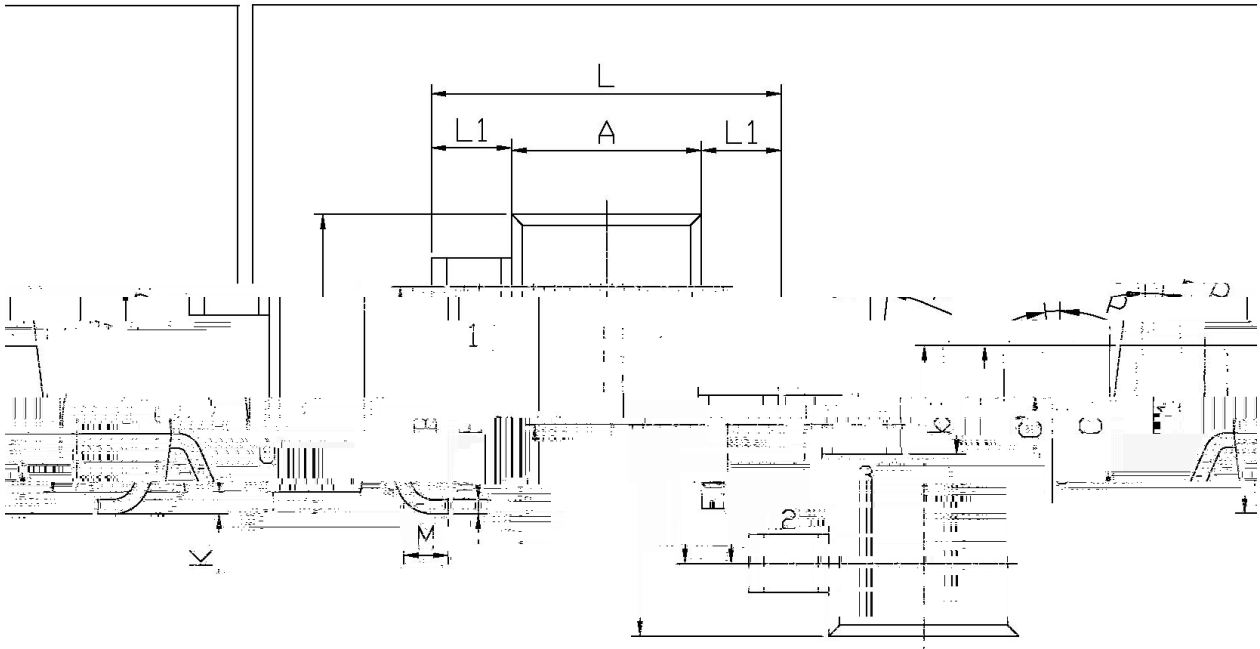


Figure 9 : Safe Operation Area



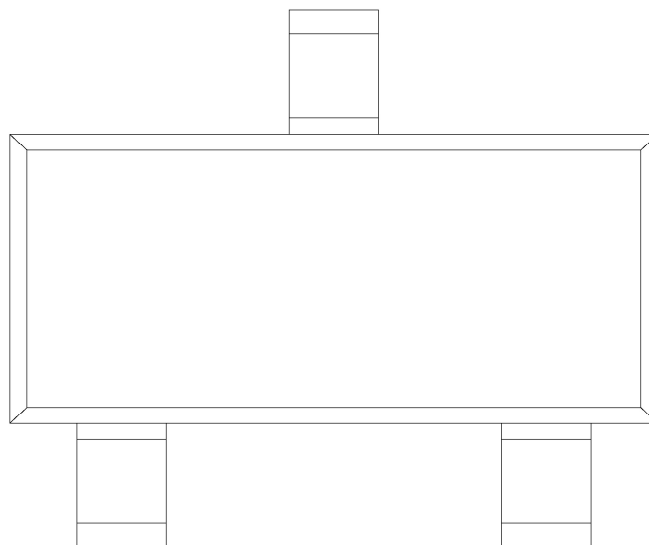
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/ Package Dimensions

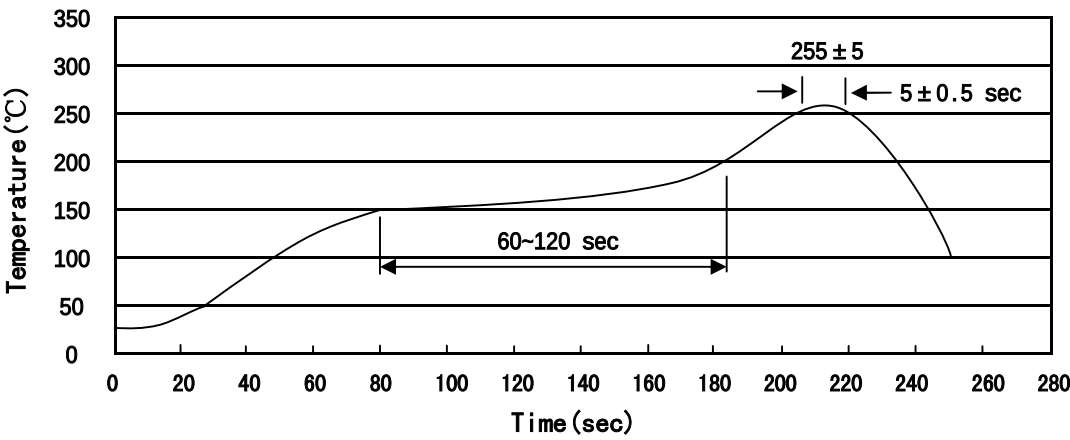


Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
L1	0.45	0.65	C1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
B	2.70	3.10	K	0	0.10
D120MIN			E 2.10 ± 0.10		
7°			e	0.85	1.05
			b	0.35	0.55

/ Marking Instructions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 、预热温度 ~ °C，时间 ~ °C
- 、峰值温度 ± °C，时间持续为 ± °C ±
- 、焊接制程冷却速度为 ~ °C °C

/ Resistance to Soldering Heat Test Conditions

温度： ± °C 时间： ± °C

/ Packaging SPEC.

卷盘包装

封装形式	包装数量					包装尺寸		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

/ Notices